OMB No. 0651-0027  To the Honorable Commissioner of Pater  1. Name of conveying party(ies):  Akiko MATSUMURA Yuji HOTTA Sadahito MISUMI  Additional name(s) of conveying party(ies) attached? □ Yes ☑ No	U.S. DEPARTMENT OF COMMERC U.S. Patent and Trademark Offic  2143544  2. Name and address of receiving party(ies):  NITTO DENKO CORPORATION 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka, Japan
3. Nature of conveyance:  ☑ Assignment ☐ Merger  ☐ Security Agreement ☐ Change of Name  ☐ Other	
Execution Date: June 19, 2002 4. Application number(s) or patent number(s):	Additional name(s) & address(es) attached? ☐ Yes ☑ No
If this document is being filed together with a new application, the execution date of the application is: June 19, 2002	
A. Patent Application No.(s)	B. Patent No.(s)
Additional numbers	attached? □ Yes ☑ No
5. Name and address of party to whom correspondence concerning document should be mailed:  SUGHRUE MION, PLLC 2100 Pennsylvania Avenue, N.W. Suite 800 Washington, D.C. 20037-3213	6. Total number of applications and patents involved:  1 7. Total fee (37 CFR 3.41): \$40.00  ☑ Enclosed.  ☐ Authorized to be charged to Deposit Account No. 19-4880.  The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.  8. Deposit account number:
	19-4880 (Attach duplicate copy of this page if paying by deposit account)
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9. Statement and signature.  To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.	
Mark Boland Reg. No.	June 24, 2002  32,197  Date  cover sheet, attachments, and documents: 2
Mail documents to be recorded with required cover sheet information to:  Commissioner of Patents & Trademarks  Box Assignment  Washington, D.C. 20231	

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PATENT REEL: 013032 FRAME: 0253

## **ASSIGNMENT**

Whereas, \*/we Akiko MATSUMURA, Yuji HOTTA and Sadahito MISUMI, all of Osaka, Japan

hereinafter called assignor(s), have invented certain improvements in

PROCESS FOR PRODUCING SEMICONDUCTOR WAFER WITH ADHESIVE FILM

and executed an application for Letters Patent of the United States of America therefor on

June 19, 2002; and

Whereas,

NITTO DENKO CORPORATION

1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka, Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged.

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. § 119, and I/we request the Director – U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request my/our attorneys SUGHRUE MION, PLLC of 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3213 to insert here in parentheses (Application number\_\_\_\_\_\_, filed\_\_\_\_\_\_\_) the filing date and application number of said application when known.

Date: June 19, 2002	si Ukiko Matsumura
<b>Date</b> : June 19, 2002	s/ Gryi Hilla
<b>Date</b> : June 19, 2002	s/ Soclahito Misumi
Date:	s/
Date:	s/

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. §261)

RECORDED: 06/24/2002

PATENT REEL: 013032 FRAME: 0254